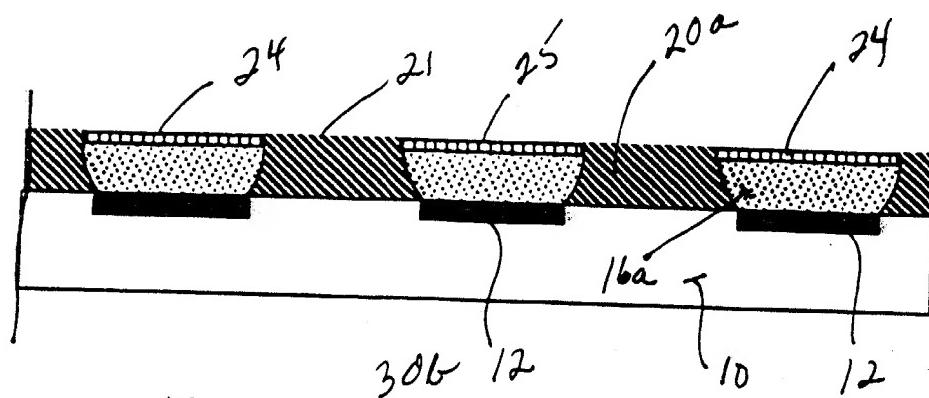


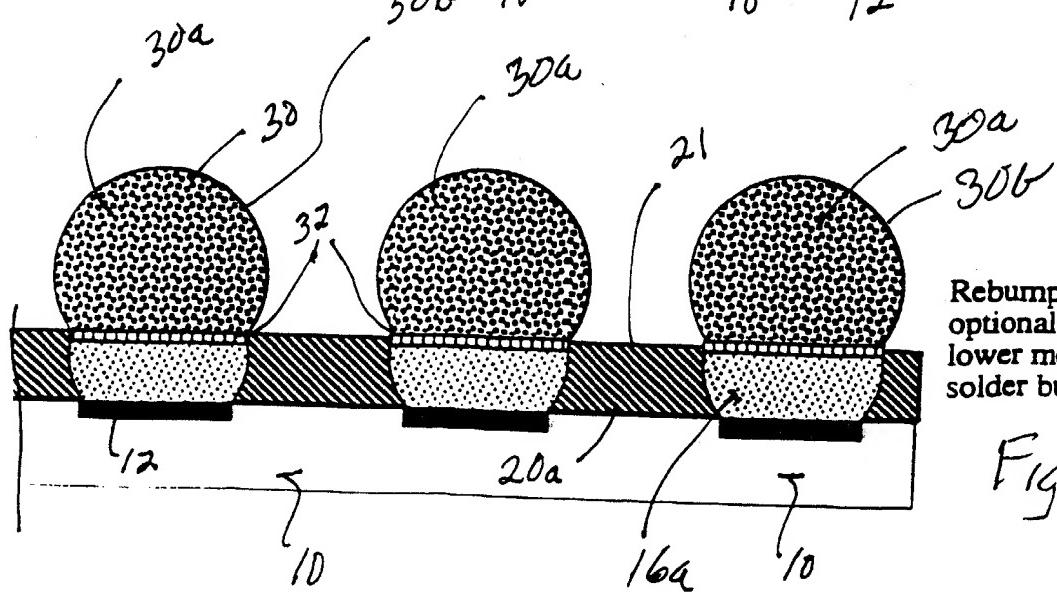
Grind off Polymeric layer to expose bumps, optional light solder etch to remove solder residue from polymeric surface and reduce bump height.

Fig 4A.



Optional diffusion Barrier deposition

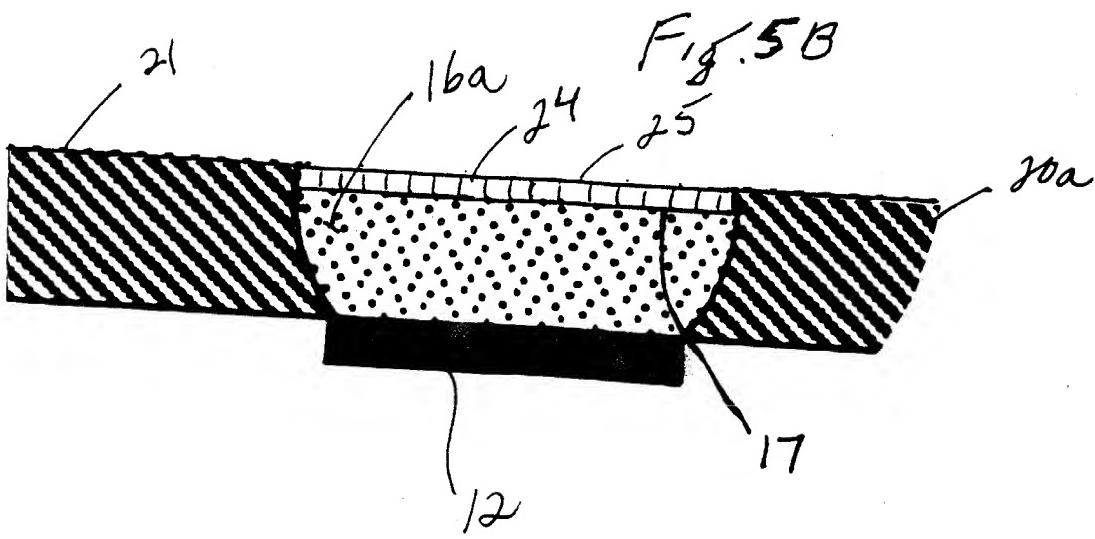
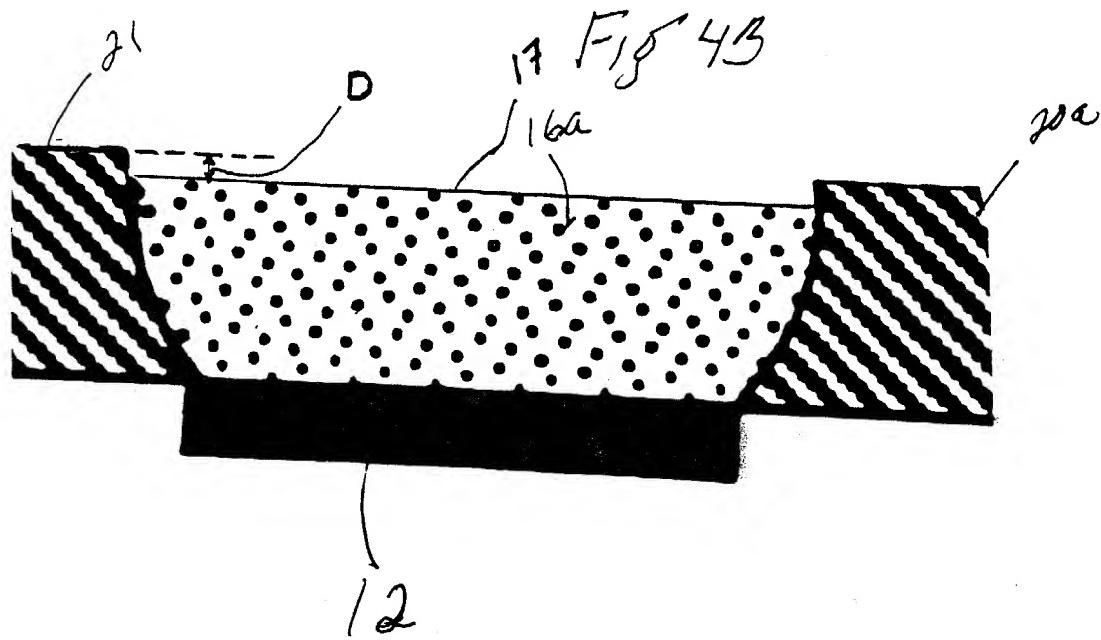
Fig 5A

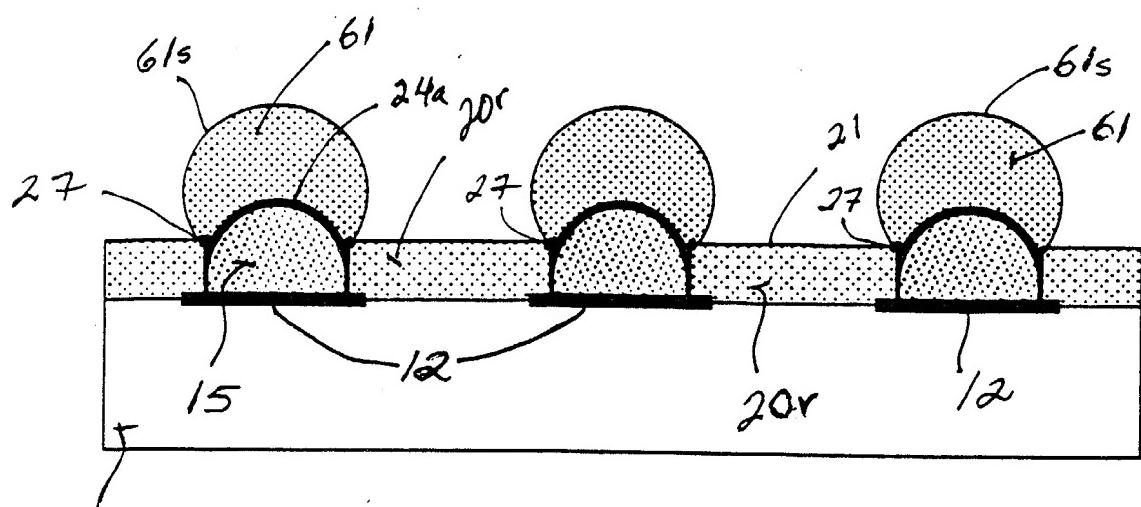


Rebump : shown with optional barrier layer and lower melting point second solder bumping

Fig 6

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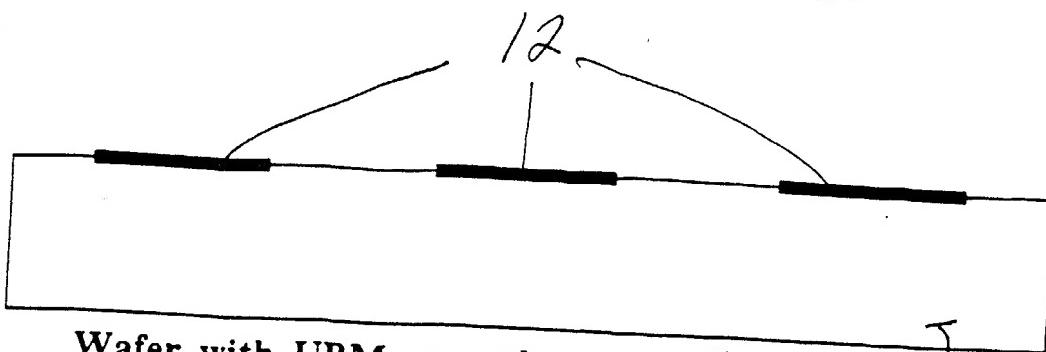




10

- A wafer bumping structure

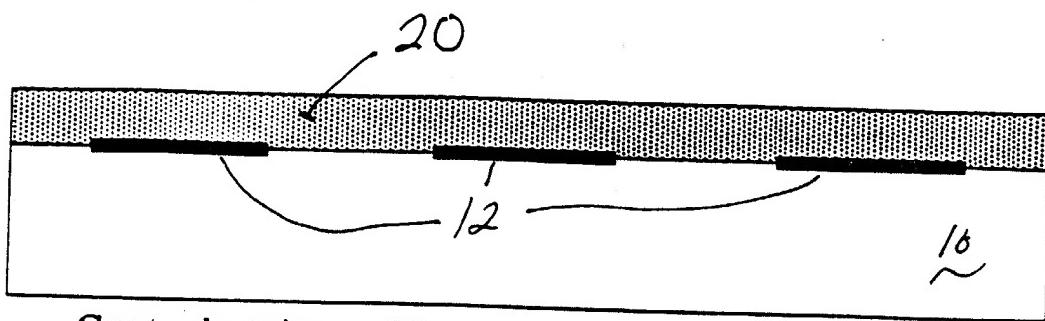
Fig 7



Wafer with UBM on pads
(redistribution as necessary)

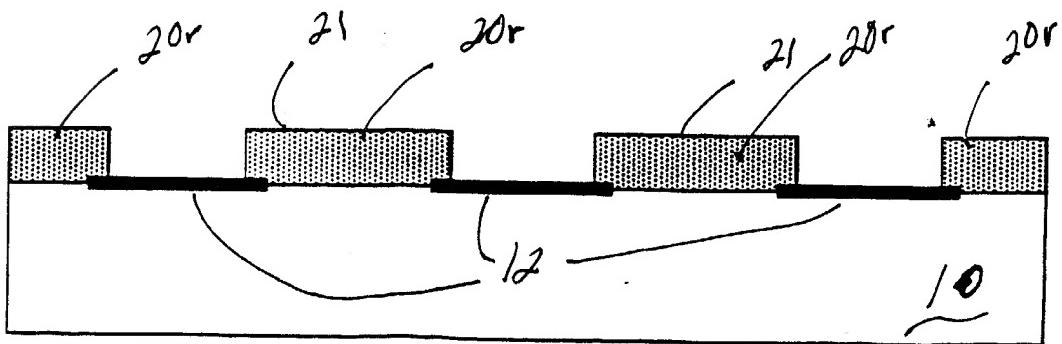
Fig 8

10



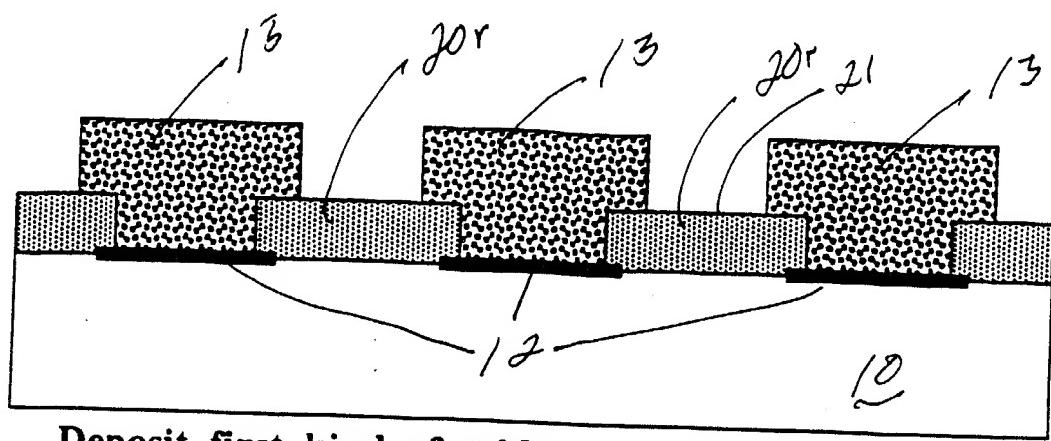
Coat photoimagable polymeric layer

Fig 9



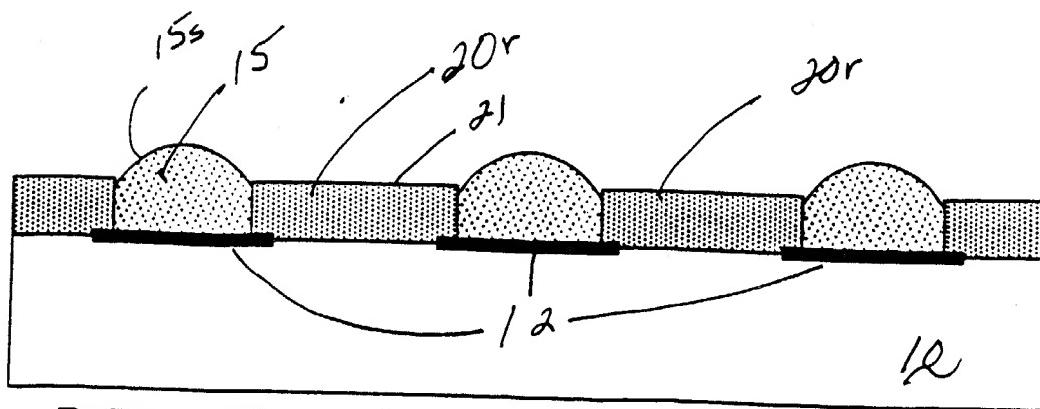
Photolithography to open pad

Fig 10



Deposit first kind of solder paste

Fig 11



Reflow wafer to form solder bump
Clean flux residual

Fig 12A

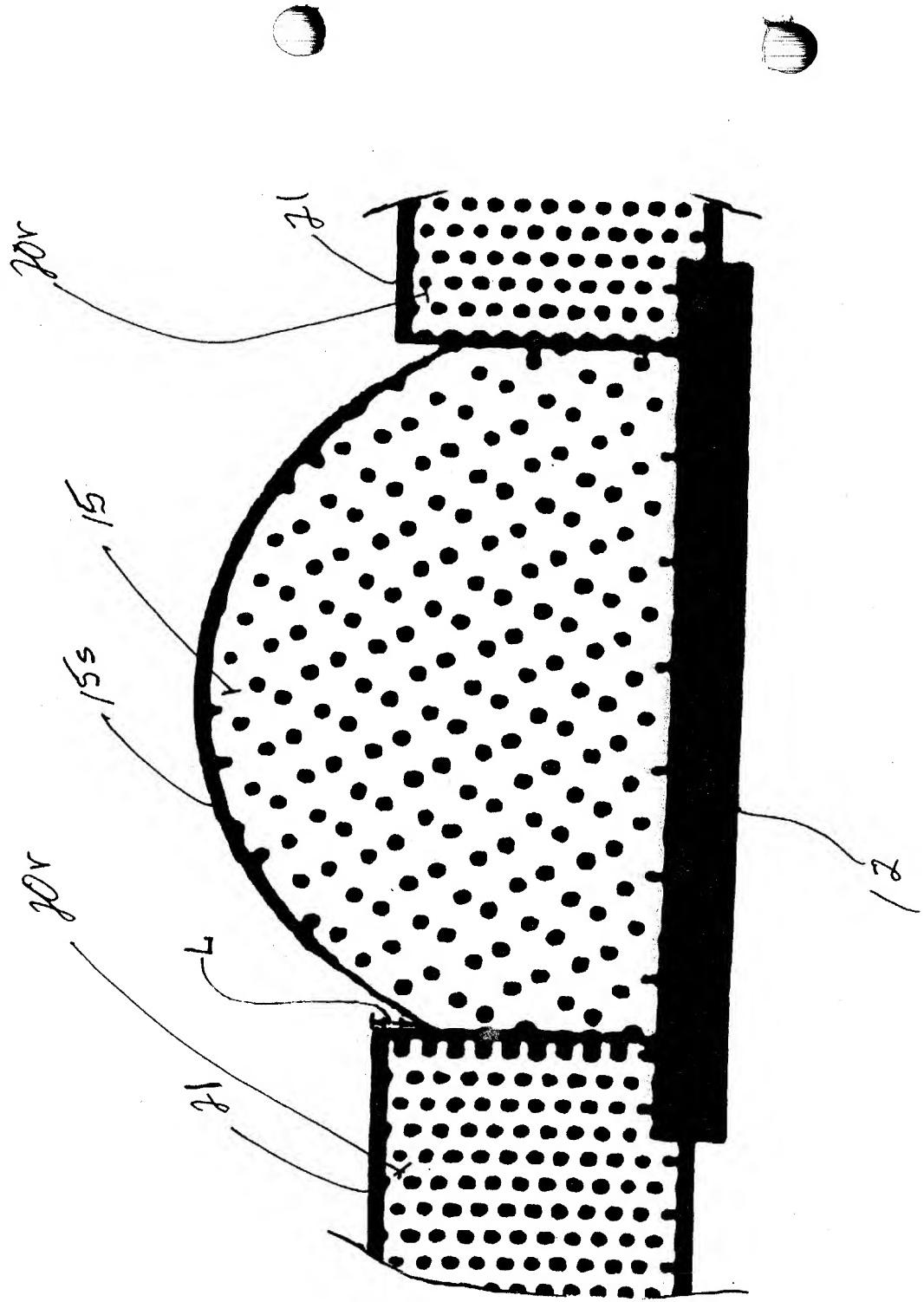
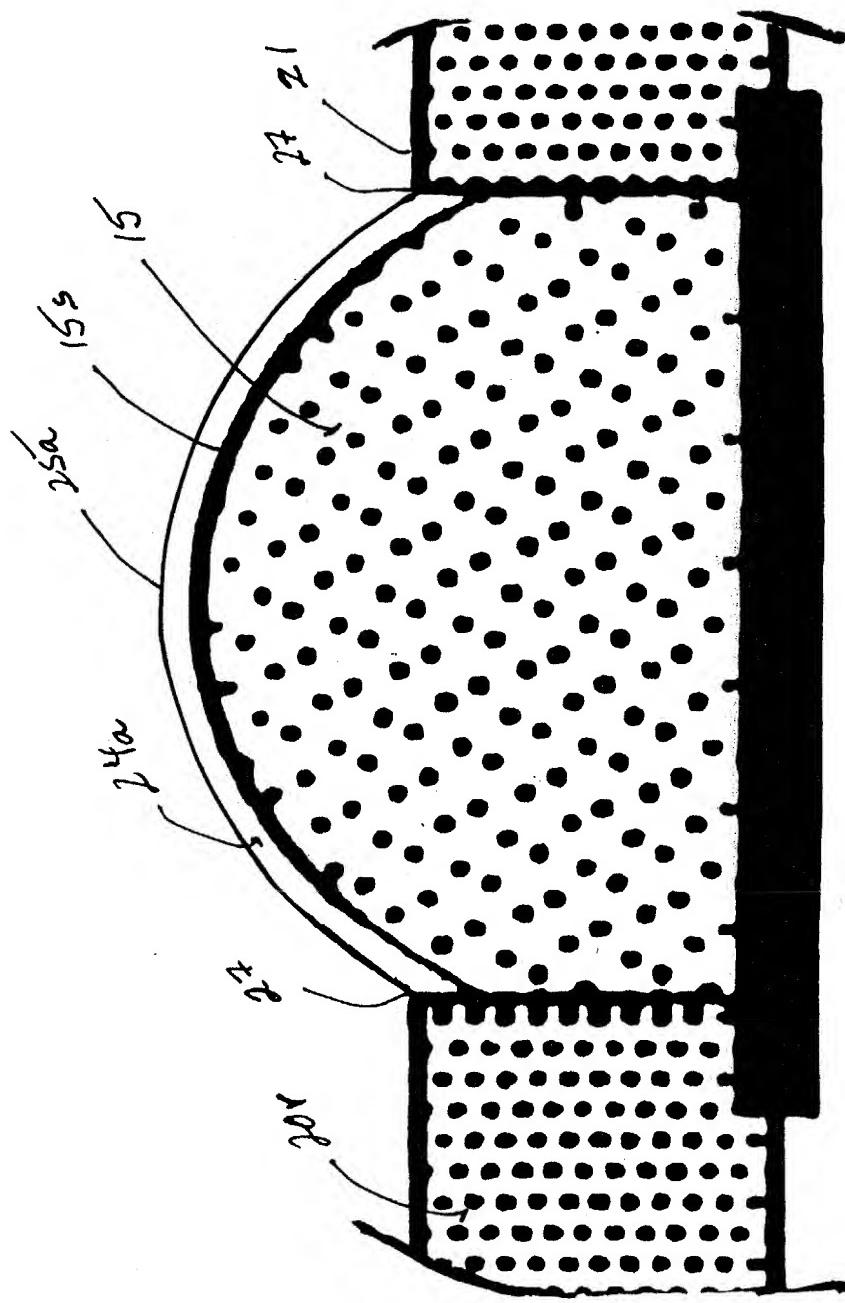
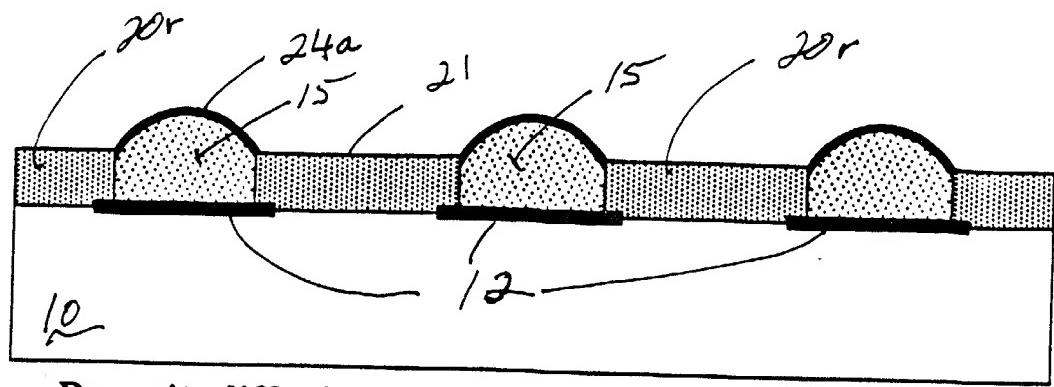


Fig 12B

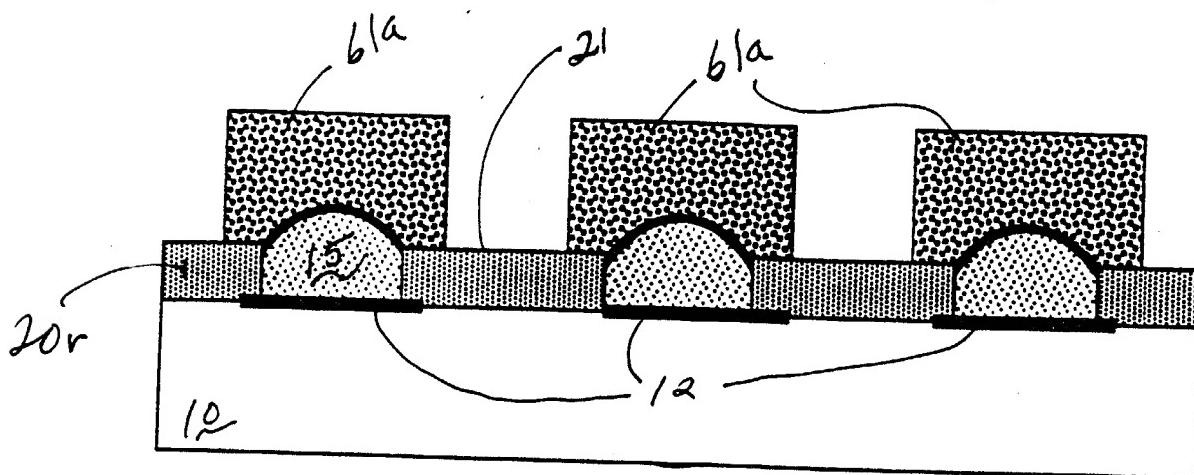
Fig 18c





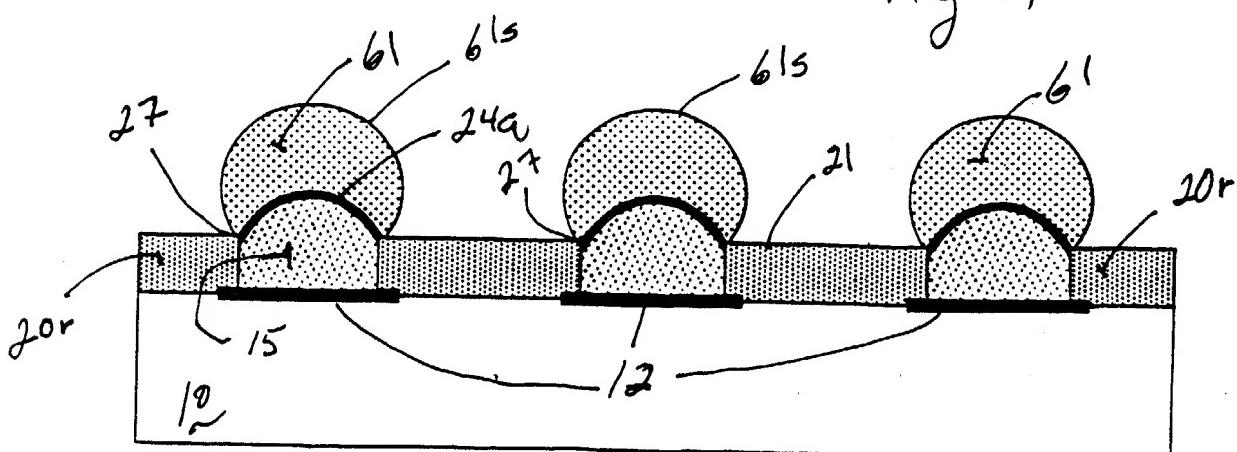
Deposit diffusion barrier

Fig 13



Deposit second kind of solder paste

Fig 14



**Reflow wafer to form solder bump
Clean flux residual**

Fig 15